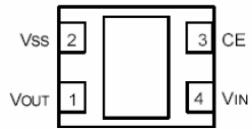
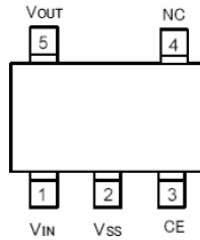


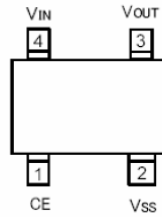
PIN CONFIGURATION



USP-4
(BOTTOM VIEW)



SOT-25
(TOP VIEW)

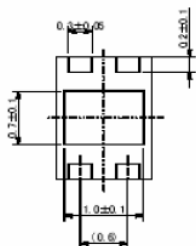
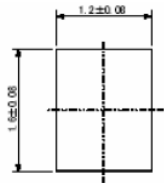


SSOT-24
(TOP VIEW)

*The heat dissipation pad of the USP-4 package is recommended to solder as the recommended mount pattern and metal mask pattern for mounting strength. The mount pattern should be electrically opened or connected to the VSS (#2) pin.

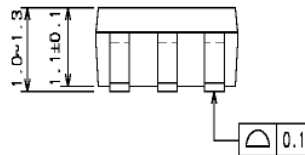
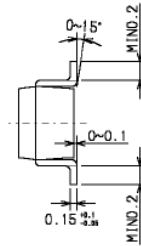
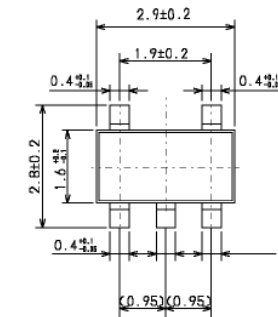
PACKAGING INFORMATION

● USP-4



* Soldering fillet surface is not formed because the sides of the pins are plated.

● SOT-25 (SOT-23-5)



● SSOT-24

